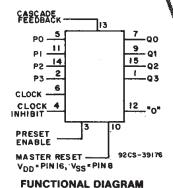


Data sheet acquired from Harris Semiconductor SCHS079C – Revised October 2003

RECOMMENDED FOR

CD4522B Types

Advance Information/ **Preliminary Data**



CMOS Programmable BCD Divide-by-"N" Counter

Features:

- Internally synchronous for high internal and external speeds.
- Logic edge-clocked design increments on positive Clock transition or on negative Clock Inhibit transition.
- 100% tested for quiescent current at 20-V.
- 5-V, 10-V, and 15-V parametric ratings.
- High-Voltage Types (20-Volt Rating) Standard symmetrical output characteristics.
 - Maximum input current of 1 µA at 18 V over full package-temperature range: 100 nA at 18 V and 25° C.
 - Meets all requirements of JEDEC Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices."

CD4522B programmable BCD counter has a decoded "0" state output for divide-by-N applications. In single stage operation the "0" output is tied to the Preset Enable input. The Cascade Feedback allows multiple stage divide-by-N operation without the need for external gating. A HIGH on the Clock Inhibit disables the pulse-counting function. A HIGH on the Master Reset asynchronously resets the divide-by-N operation. The output is presented in BCD format.

The CD4522B-series types are supplied in 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

Applications:

- Frequency synthesizers
- Phase-locked loops
- Programmable down counters
- Programmable frequency dividers

MAXIMUM RATINGS, Absolute-Maximum Values: DC SUPPLY-VOLTAGE RANGE, (VDD)

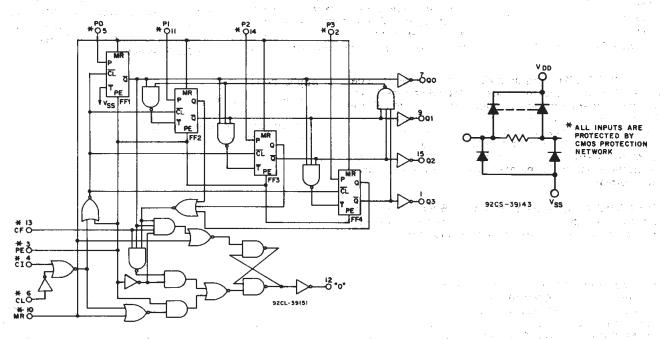
0.5V to +20V	voltages referenced to VSS Terminal)
-0.5V to V _{DD} +0.5V	INPUT VOLTAGE RANGE, ALL INPUTS
±10mA	DC INPUT CURRENT, ANY ONE INPUT
	POWER DISSIPATION PER PACKAGE (PD):
500mW	For T _A = -55°C to +100°C
Derate Linearity at 12mW/°C to 200mW	For T _A = +100°C to +125°C
•	DEVICE DISSIPATION PER OUTPUT TRANSISTOR
	FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)
	OPERATING-TEMPERATURE RANGE (TA)
65°C to +150°C	STORAGE TEMPERATURE RANGE (Tsig)
	LEAD TEMPERATURE (DURING SOLDERING):
+265°C	At distance $1/16 \pm 1/32$ inch $(1.59 \pm 0.79$ mm) from case for 10s max

TRUTH TABLES

CLOCK	CLOCK INHIBIT	PRESET ENABLE	MASTER RESET	ACTION
0	0	0	0	No Count
_	0	0	0	Count Down
X	1	0	0	No Count
[1]	\sim	0	0	Count Down
Х	Х	1	0	Preset
Х	х	Х	1	Reset

X = Don't Care

_		OUTPUTS									
Count	Qo	Q ₀ Q ₁ Q ₂									
0	0	0	0	0							
1	1 1	0	0	- 0							
(2 · -)	0	1	0	0							
3-2 3	ers (fish)	1	0	0							
4	0	0	1	0							
5	1 9	0	. 1	0 '							
6	0	1 .	1	0 1							
7	1	1	1	0							
8 🚉	0	0	0	1							
9	1 7	0 ,	0	1							



a. Basic diagram.

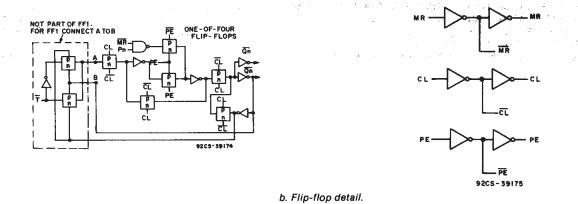


Fig. 1 - Logic diagram for the CD4522B.

RECOMMENDED OPERATING CONDITIONS at $T_A = 25^{\circ}$ C, except as noted.

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTICS		LIN	IITS	UNITS	
CHARACTERISTICS	(V)	Min.	Max.	UNITS	
Supply-Voltage Range (For T _A = Full Package- Temperature Range		3	18	v	
Pulse Width: Clock, tw(cc)	5 10 15	250 100 80		ns	
Preset Enable, tw(cc)	5 10 15	250 100 80	_	ns	
Master Reset, tw(_{MR})	5 10 15	350 250 200	-	пѕ	
Clock Frequency, fcL	5 10 15	_	1.5 3.0 4.0	MHz	
Clock Rise and Fall Time t _{rct} , t _{rct}	5 10 15		15 15 15	μs	
Preset Enable Set-up Time, t _{su}	5 10 15	0 0 0	_ _ _	ns	
Preset Enable Hold Time, t _h	5 10 15	75 25 20		ns	
Master Reset Removal Time, t _{rem}	5 10 15	130 50 30		ns	

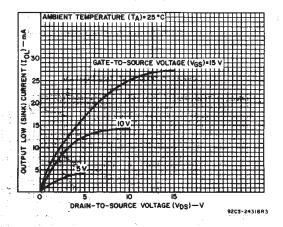


Fig. 2 — Typical output low (sink) current characteristics.

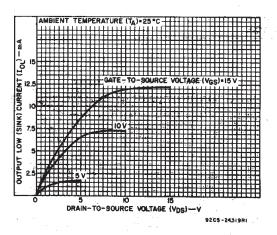


Fig. 3 — Minimum output low (sink) current characteristics.

STATIC ELECTRICAL CHARACTERISTICS

CHARACTER- ISTIC	cc	NOITION	IS	LI	MITS AT	INDICA	TED TE	MPERAT	UNITS		
	V _o	Vin	V _{DD}			.	,		+25		
	(V)	(V)	(V)	-55	-40	+85	+125	Min.	, Тур.	Max.	
Quiescent Device		0, 5	5	5	5	150	150		0.04	5	
Current, IDD Max.		0, 10	10	10	10	300	300		0.04	10	
		0, 15	15	20	20	600	600		0.04	20	μΑ
		0, 20	20	100	100	3000	3000	-	0.08	100	
Output Low	0.4	0, 5	5	0.64	0.61	0.42	0.36	0.51	1]
(Sink) Current	0.5	0, 10	10	1.6	1.5	1.1	0.9	1.3	2.6		
I _{OL} Min.	1.5	0, 15	15	4.2	4	2.8	2.4	3.4	6.8	· —	
Output High	4.6	0, 5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1		mA
(Source)	2.5	0, 5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2]
Current,	9.5	0, 10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6]
Iон Min.	13.5	0, 15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8		
Output Voltage:		0, 5	5		0.	05			0	0.05]
Low-Level,		0, 10	10		0.	05			0	0.05]
V _{OL} Max.		0, 15	15		0.	05			0	0.05]
Output Voltage:		0, 5	5		4.	95		4.95	5	[_
High-Level	_	0, 10	10		9.	95		9.95	10	_	
V _{он} Min.		0, 15	15		. 14	.95		14.95	15		V
Input low	0.5, 4.5	-	5		1	.5			_	1.5] `
Voltage, V _{IL} Max.	1, 9		10	3				_	_	3]
	1.5, 13.5		15	4				_	_	4	
Input High	0.5, 4.5	_	5		3	.5		3.5		_	
Voltage, V _{IH} Min.	1, 9		10	7				7			
-	1.5, 13.5	_	15		1	1		11	<u> </u>	_	
Input Current, I _{IN} Max.	_	0, 18	- 18	±0.1	±0.1	±1.	±1		±10 ⁻⁵	±0.1	μΑ

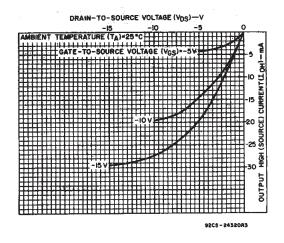


Fig. 4 — Typical output high (source) current characteristics.

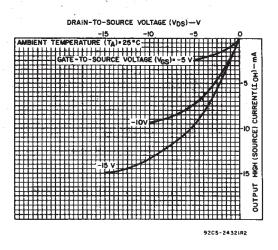
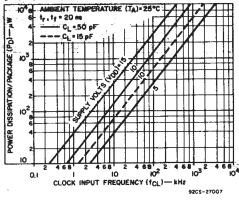
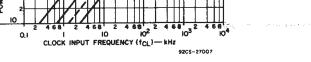


Fig. 5 — Minimum output high (source) current characteristics.

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A=25^{\circ}C$, Input t_r , $t_f=20$ ns, $C_i=50$ pF, R_L , =200 k Ω

0114.04.6777.077.0	TEST CO	NDITIONS]			
CHARACTERISTIC		V _{DD} (V)	Min.	Тур.	Max.	UNITS	
Propagation Delay Time; t _{PHL} , t _{PLH:}		5		550	1100		
Clock to "Q" outputs		10		225	450	ns	
		15		160	320	 	
8 -		5	· —	420	710		
Clock to "0" output		10	-	160	270 190	ns	
		15		110		-	
Olimpia imbilità del HOII essante		5	-	270	540 200	ns	
Clock inhibit to "Q" outputs		10 15	_	100 70	140	113	
		5		270	540	-	
Master reset to "Q" outputs		10		100	200	ns	
Master reset to a outputs		15	_	70	140	"	
		5		0	0		
Preset Enable Setup Time, t _{su}		10	_	0	0	ns	
		15		0	0		
		5		75	150		
Preset Enable Hold Time, t _h		10		25	50	ns	
:		15		20	40	-	
		5	_	130	260		
Master Reset Removal Time, trem		10	_	50	100	ns	
			_	30		+	
		5	_	100 50	200 100	ns	
Transition Time, t _{THL} , t _{TLH}	-	10 15	, =	40	80	113	
Minimum Pulse Width	. /	5		125	250	1	
		10		50	100	ns	
Clock, twicL)		15	<u> </u>	40	80		
		5		125	250		
Preset Enable, tw(PE)		10	_	50	100	ns	
		15		40	80	1	
	en i tir trati e e tra e e e e e e e e e e e e e e e e e e e	5	_	175	350		
Master Reset, twime		10	-	125	250	ns	
		15		100	200	-	
_		5	-	3	1.5	1	
Max Clock Freq, fcL	Ì	10 15		6 8	3.0 4.0	MHz	
Ol La Milia Dissa		5	6		15	-	
Max Clock or Clock Inhibit Rise &		10	- =		15	us	
Fall Time, t _{TLH} , t _{THL}	· (4.0	15		_	15		
	<u> </u>		1	<u> </u>	4		





16 ADD . 15 Q2 P2 13 12 90 10 VIEW 92CS-39177

TERMINAL ASSIGNMENT

Fig. 6 — Typical dynamic power dissipation vs. frequency.

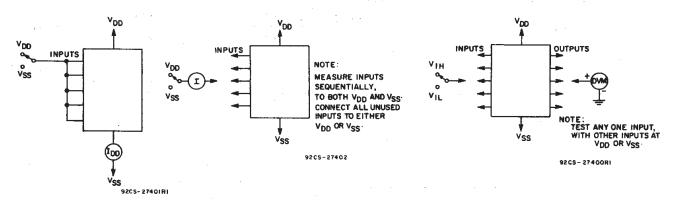
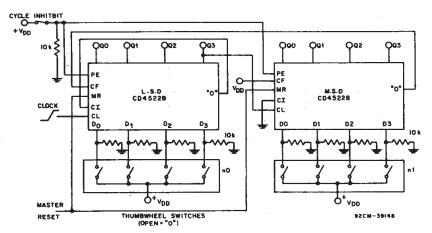


Fig. 7 — Quiescent device current test circuit.

Fig. 8 — Input current test circuit.

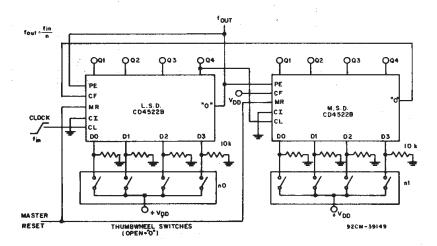
Fig. 9 — Input voltage test circuit.

APPLICATION CIRCUITS



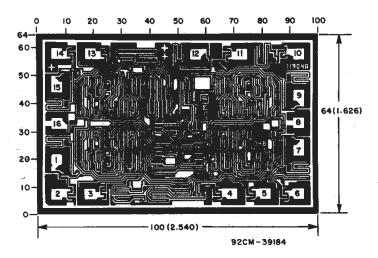
Fro	m	To	•	Donne of N			
Stage	Pin	Stage	Pin	Range of N			
LSD	"0"	Ali	PE	LSD < N < MSD			
N	"0"	N-1	CF	LSD+1 <n<msd< td=""></n<msd<>			
N	"0₃"	N+1	CL	LSD < N < MSD-1			

Fig. 10 — 2-Stage Programmable Down Counter (One Cycle)



Fro	m	To)	Dence of N			
Stage	Płn	Stage	Pin	Range of N			
LSD	"0"	All	PE	LSD < N < MSD			
N	"0"	N-1	CF	LSD + 1 < N < MSD			
N.	"03"	N+1	CL	LSD < N < MSD-1			

Fig. 11 — 2-Stage Programmable Frequency Divider



Dimensions and pad layout for CD4522BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CD4522BE	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4522BE	Samples
CD4522BM	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM	Samples
CD4522BMT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM	Samples
CD4522BPW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM522B	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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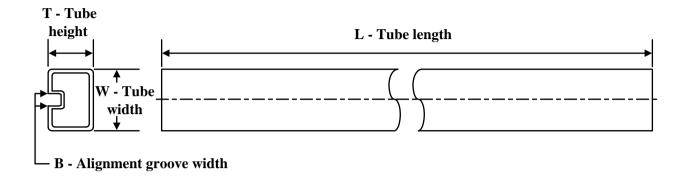
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PACKAGE MATERIALS INFORMATION

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TUBE

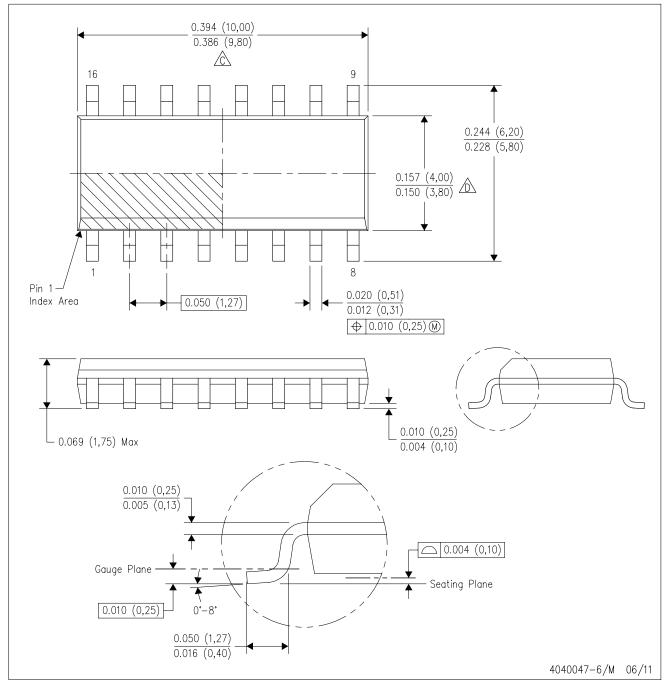


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD4522BE	N	PDIP	16	25	506	13.97	11230	4.32
CD4522BE	N	PDIP	16	25	506	13.97	11230	4.32
CD4522BM	D	SOIC	16	40	507	8	3940	4.32
CD4522BPW	PW	TSSOP	16	90	530	10.2	3600	3.5

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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